CLAIMS

1. An electro-acoustic transducer comprising:

a case molded integrally with a frame at the bottom;

a heat-curing and UV(ultra violet ray)-curing adhesive layer formed on said frame;

a magnet bonded on said frame via said heat-curing and UV-curing adhesive layer; and

a diaphragm provided above said magnet.

2. A method of manufacturing electro-acoustic transducers comprising steps of:

a. forming a layer of a heat-curing and UV-curing adhesive on a frame integrally molded at the bottom of a case, and disposing a magnet on said frame via said layer of a heat-curing and UV-curing adhesive;

b. irradiating UV light to said case, with said magnet placed thereon, so that said heat-curing and UV-curing adhesive is cured in the portion exposed to the UV light;

c. heating, after curing said heat-curing and UV-curing adhesive, said heat-curing and UV-curing adhesive so that said magnet is bonded on said frame; and

d. mounting, after said magnet is bonded on said frame, a diaphragm above said magnet.

3. An electro-acoustic transducer comprising:

a case molded integrally with a frame at the bottom;

a magnet mounted on said frame with an adhesive,

a UV-curing resin layer formed on said case having said magnet mounted thereon, and

a diaphragm provided above said magnet.

4. The electro-acoustic transducer of claim 3, wherein the adhesive bonding said magnet on said frame is a heat-curing adhesive.

5. A method of manufacturing electro-acoustic transducers comprising steps of:

a. forming a heat-curing adhesive layer on a frame integrally molded at the bottom of a case, and disposing a magnet on said frame via said heat-curing adhesive layer;

b. forming a UV-curing resin layer on said case mounted with said magnet thereon;

c. irradiating UV light to said case, after said UV-curing resin layer is formed thereon, so that said UV-curing resin is cured;

d. heating, after said UV-curing resin is cured, the heat-curing adhesive layer so that said magnet is bonded on said frame; and

e. mounting, after said magnet is bonded on said frame, a diaphragm above said magnet.